



Product Change Notification

Change Notification #: 116586 - 00
Change Title: Intel® Server System R1304WTTGSR, PCN 116586-00, Product Design, Rear panel and rear brackets new design, Factory Firmware update, Grommet color change.
Date of Publication: November 12, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:*	November 27, 2018
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

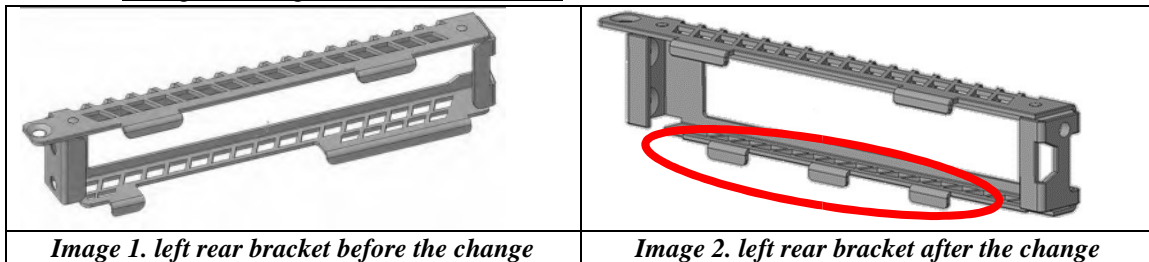
Description of Change to the Customer:

Intel is implementing the next changes in the Intel® Server System R1304WTTGSR.

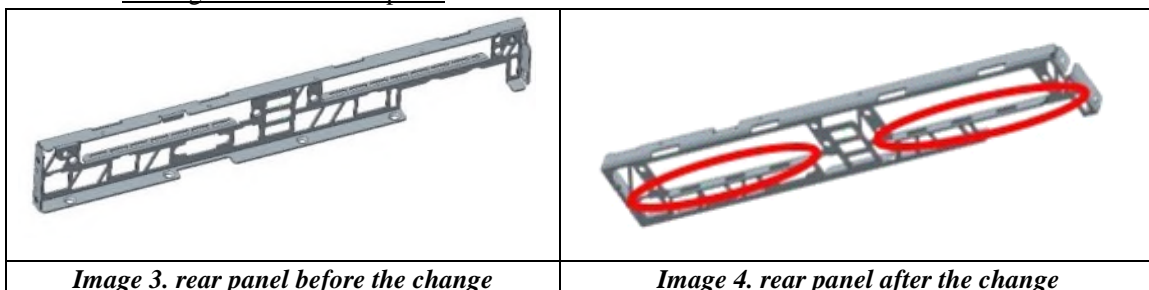
This PCN follows to **PCN 116118 – 05**

Change 1: To improve the connection of Small Form-factor Pluggable transceiver (SFP+) cables on the rear panel and the miniSAS connection. This change requires to change the MM# from 943891 to 977052.

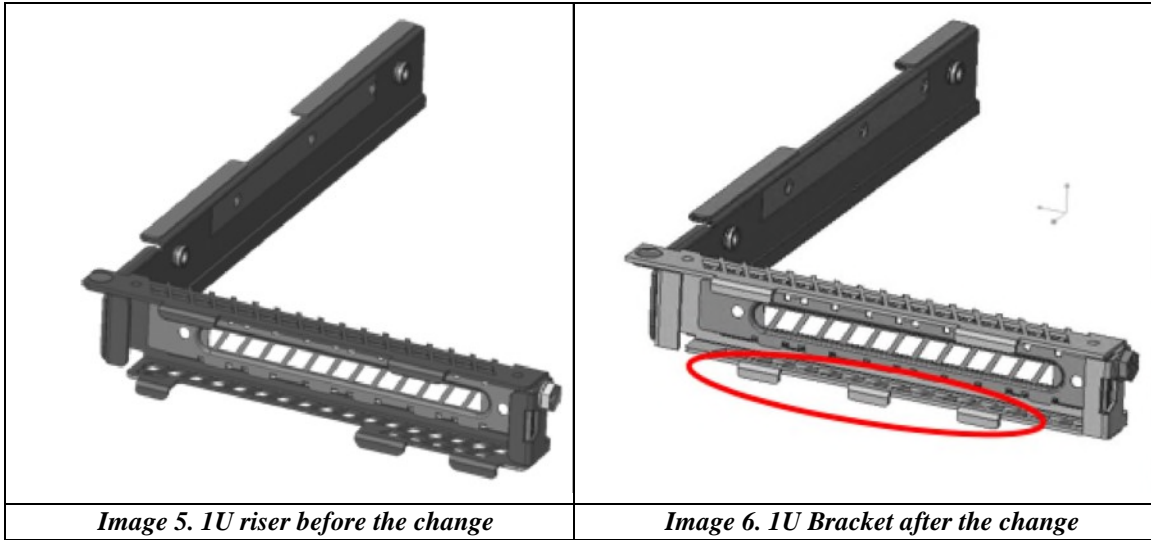
1. Change the design of the left rear bracket



2. Adding holes to the rear panel



3. Riser bracket new design.



Change 2: Intel® is changing the color on the Fan holding Grommet J76819 (See below images).

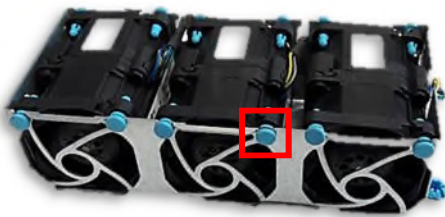


Image 7. Fan holding Grommet previous changes (color is blue)

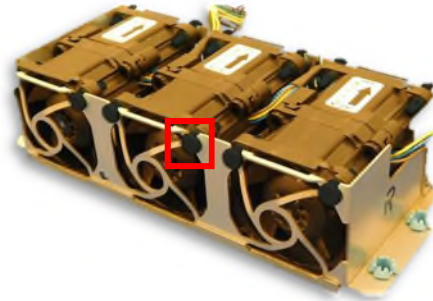


Image 8. Fan holding Grommet with the changes (color is black)

Change 3: Intel is implementing the following Firmware updates:

- i Update the BIOS to revision R01.01.2024.
- ii Update the Manageability Engine (ME) firmware to revision 03.01.03.043.
- iii Update the Integrated Baseboard Management Controller (BMC) firmware to revision 01.51.11142.

Intel Server Boards with factory firmware will display the following message on each boot until the BIOS is updated:

"WARNING: This Server is running factory firmware. A software update is required. As part of your system integration process, please load the latest system update package (SUP) to enable the latest security, quality and performance."

Customer Impact of Change and Recommended Action:

Intel recommend to the customers to perform a fit check on their systems and chassis based on this new chassis rear bracket design.

The primary value of FW factory BIOS update is that it allows the customer to perform a single BIOS programming (upgrade or downgrade) without the requirement of moving the BIOS Recovery physical jumper. Once the first programming is done, any subsequent attempts to downgrade will require moving the BIOS Recovery physical jumper.

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>

Contact your local Intel Field Sales Rep if you have any further questions about these changes

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R1304WTTGSR	977052	J11482-009	J11482-010

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 12, 2018	00	Originally Published PCN



Product Change Notification

116586 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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